L Number	Hits	Search Text	DB	Time stamp
1	9417		USPAT;	2004/02/18 14:47
	-	near3 (positioning or position or positioned	US-PGPUB;	
		or locating or located or aligning or	EPO; JPO;	
		alignment or aligned or align) near3	DERWENT;	
		(template or aperture or socket or guide or	IBM_TDB	
.		recess)		
2	278	(chip or ic or die or module or component)	USPAT;	2004/02/18 13:43
		near3 (positioning or position or positioned	US-PGPUB;	
		or aligning or alignment or aligned or align) near3 (template)	EPO; JPO; DERWENT;	
		align, nears (template)	IBM TDB	
3	99	(chip or ic or die) near3 (positioning or	USPAT;	2004/02/18 13:43
		position or positioned or aligning or	US-PGPUB;	=====================================
		alignment or aligned or align) near3	EPO; JPO;	
		(template)	DERWENT;	
			IBM_TDB	_
4	146	(chip or ic or die) near5 (positioning or	USPAT;	2004/02/18 14:04
		position or positioned or aligning or	US-PGPUB;	
		alignment or aligned or align) near3	EPO; JPO;	
		(template)	DERWENT;	·
_	_		IBM_TDB	0004/00/55 55 =5
5	9		USPAT	2004/02/18 13:59
6	1115	(chip or ic or die) near5 (positioning or position or positioned or aligning or	USPAT; US-PGPUB;	2004/02/18 14:05
			EPO; JPO;	
		alignment or aligned or align) near3 (aperture)	DERWENT;	
		(aperture)	IBM TDB	
7	392	(chip or ic or die) near5 (positioning or	USPAT;	2004/02/18 14:05
'	3,2	position or positioned or aligning or	US-PGPUB;	2001, 02, 10 11.03
		alignment or aligned or align) near3	EPO; JPO;	
		(aperture) and (silicon or semiconductor)	DERWENT;	
		-	IBM_TDB	
8	141	(chip or ic or die) near2 (aperture) near3	USPAT;	2004/02/18 14:10
i		(positioning or position or positioned or	US-PGPUB;	
		aligning or alignment or aligned or align)	EPO; JPO;	
		and (silicon or semiconductor)	DERWENT;	
	120	(*)-i	IBM_TDB	2004/02/10 14 10
9	130	(chip or ic or die) near5 (mounting or mounted or bonding or bonded or flip adj	USPAT;	2004/02/18 14:18
		chip or packaging) near3 (alignment or	US-PGPUB; EPO; JPO;	
		placement or aligning or aligned) near4	DERWENT;	
		(precise or precision or precisely or exact	IBM TDB	1
		or exactly)		
10	19	(chip or ic or die) near5 (mounting or	USPAT;	2004/02/18 14:20
		mounted or bonding or bonded or flip adj	US-PGPUB;	
		chip or packaging) near3 (alignment or	EPO; JPO;	
i		placement or aligning or aligned) near4	DERWENT;	
1 1 1	0.000	(sidewall or wall)	IBM_TDB	2004/02/22 24 24
11	2703		USPAT;	2004/02/18 14:24
		received or inserting or insertion or inserted or holding or aligning or	US-PGPUB; EPO; JPO;	
		alignment) near2 (recess or slot or	DERWENT;	
		aperture)	IBM TDB	
12	1664		USPAT;	2004/02/18 14:24
		received or inserting or insertion) near2	US-PGPUB;	
[		(recess or slot or aperture)	EPO; JPO;	
		_	DERWENT;	
			IBM_TDB	
13	106	,	USPAT;	2004/02/18 14:28
		received or inserting or insertion) near2	US-PGPUB;	
		(recess or slot or aperture) near6 (template	EPO; JPO;	
	!	or self-aligned or self-alignment or walls	DERWENT;	
14	_	or guide or sidewall or ramp)	IBM_TDB	2004/02/10 14 32
14	2	5824186.pn.	USPAT; US-PGPUB;	2004/02/18 14:32
]			EPO; JPO;	
			DERWENT;	
			IBM TDB	
15	2	("4990462"   "5091045").PN.	USPAT	2004/02/18 14:28
_16	19	5824186.URPN.	USPAT	2004/02/18 14:28

17	326	(optical) near4 (module or component or ic or chip or die) near5 (array or matrix)	USPAT; US-PGPUB;	2004/02/18 14:43
		near5 (alignment or aligning or aligned or	EPO; JPO;	
1		positioning or placement or positioned)	DERWENT;	
18	394	(chip or ic or die) near2 (self-alignment or	USPAT;	2004/02/18 14:43
		self-aligning or self-aligned)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
19	25	(chip or ic or die) near2 (self-alignment or	USPAT;	2004/02/18 14:44
		self-aligning or self-aligned) near5 (aperture or recess or slot or socket or	US-PGPUB; EPO; JPO;	
		opening or depression)	DERWENT;	
			IBM_TDB	
20	26	<pre>(chip or ic or die) near2 (self-alignment or self-aligning or self-aligned) near5</pre>	USPAT; US-PGPUB;	2004/02/18 14:44
		(aperture or recess or slot or socket or	EPO; JPO;	
•		opening or depression or wall or sidewall)	DERWENT;	
21	395	(chip or ic or die or module or component)	IBM_TDB USPAT;	2004/02/18 14:46
	333	near3 (positioning or position or positioned	US-PGPUB;	2001, 02, 10 11.10
		or locating or located or aligning or	EPO; JPO;	
		alignment or aligned or align) near3 (template or aperture or socket or quide or	DERWENT; IBM TDB	
		recess) and (template or aperture or socket	15/1_155	
		or guide or recess) near3 (metal or		
22	30	epitaxial) (chip or ic or die or module or component)	USPAT;	2004/02/18 14:49
22	30.	near3 (positioning or position or positioned	US-PGPUB;	2004/02/18 14.49
		or locating or located or aligning or	EPO; JPO;	
		alignment or aligned or align) near3 (template or guide or wall or sidewall)	DERWENT; IBM TDB	
		near3 (metal or epitaxial or aluminum or	TEM_IDE	
		titanium or tungsten or nickel or chromium)		